

Examiner's Copy

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TI **Silver-containing tin-base solder**
IN Daigo, Takashi; Watanabe, Osamu
PA Tokuriki Honten Kk, Japan
SO Jpn. Kokai Tokkyo Koho, 4 pp.
CODEN: JKXXAF

DT Patent
LA Japanese

FAN.CNT 1

	PATENT NO.	KIND	DATE	APPLICATION NO.	DATE
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PI	JP 06269981	A2	19940927	JP 1993-58543	19930318
PRAI	JP 1993-58543		19930318		
AB	A solder contains Ag 5-20, Sn 70-90, Cu 0.05-10, and Pd 0.05-2%. The solder has high corrosion resistance and elec. and thermal cond. and is suitable for elec. industry.				